Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4611	438/612,613,615,618.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:40
L2	1071	257/697	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:40
L3	773	257/697.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:40
L4	5376	1 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:40
L5	11	(method process) same (substrate ((circuit wiring) near1 board) carrier) same (polymer popyimide polymeric) same (pin lead) same (solder near1 reflow) same cur$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:45
L6	566	(method process) and (substrate ((circuit wiring) near1 board) carrier) and (polymer popyimide polymeric) and (pin lead) same (solder near1 reflow) and cur$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:46
L7	55	4 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:48
L8	31	"6297560"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:48